



Product Change Notification

Change Notification #: 116599 - 00
Change Title: Intel® Server System R1304WFTYS,
Intel® Server System R2308WFTZS,
Intel® 2U Rear Mount Hot Swap Drive
Bay Accessory Kit A2UREARHSDK2,
PCN 116599-00, Product Design,
Hot-Swap Back Plane Firmware Update
Date of Publication: November 19, 2018

Key Characteristics of the Change:

Product Design

Forecasted Key Milestones:

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|---|------------------|
| Date Customer Must be Ready to Receive Post-Conversion Material: * | December 4, 2018 |
|---|------------------|

* Intel appreciates the customer's desire to receive the latest revision of products. However, Intel manages inventory on a first in first out (FIFO) basis at the MM# level. Subsequently, customer requests for a specific revision of material (below the MM#) will not be supported by Intel.

Description of Change to the Customer:

Intel is updating the Hot-Swap Back Plane (HSBP) firmware from version 1.40 to 1.41 of the Intel Server Systems and accessories listed in the "Products Affected" table below.

- The firmware version 1.41 fixes a fault LED issue found on manufacturing.
- PBA of affected HSBP is changing from G94339-371 to G94339-372

Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from these changes, but encourages customers to understand the change and determine the impact on their applications.

Products Affected / Intel Ordering Codes:

| Product Code | MM# | Pre Change TA | Post Change TA |
|--------------|--------|---------------|----------------|
| R1304WFTYS | 975884 | H97411-011 | H97411-012 |
| R2308WFTZS | 975887 | H97457-010 | H97457-011 |
| A2UREARHSDK2 | 958243 | J37326-001 | J37326-002 |

PCN Revision History:

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|---|-------------------------------|--|
| Date of Revision: November 19, 2018 | Revision Number: 00 | Reason: Originally Published PCN |
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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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